

• Product Summary

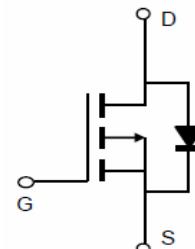
Part #	V _{DS}	R _{DS(on).typ} (@V _{GS} =10V)	R _{DS(on).typ} (@V _{GS} =4.5V)	I _D
EFM045P04F	-40V	4.3mΩ	5.5mΩ	-80A

• Description

- The EFM045P04F is the high cell density trenched
- P-chMOSFETs, which provide excellent RDSON
- and gate charge for most of the synchronous buck
- converter applications.
- The EFM045P04F meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

• Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



P-Channel MOSFET



DFN5*6-8L

• Ordering Information:

Part NO.	EFM045P04F
Marking	045P04F ****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	5000

• Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-40	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	-80	A
Drain Current-Pulsed ^(Note 1)	I _{DM}	-320	A
Maximum Power Dissipation	P _D	58	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 To 150	°C

• Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	R _{θJA}	50	°C/W
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• Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

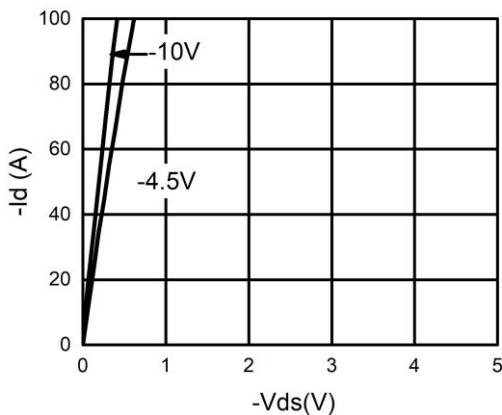
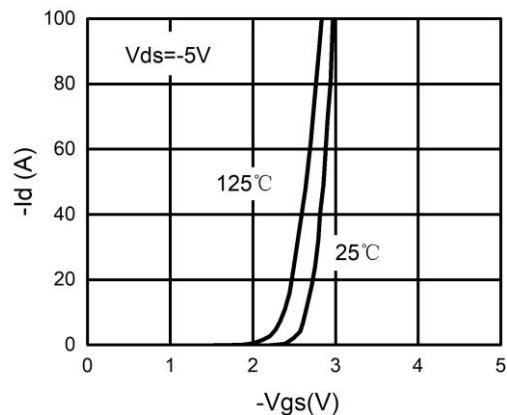
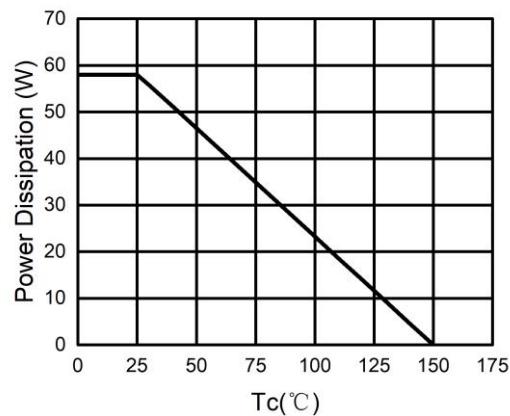
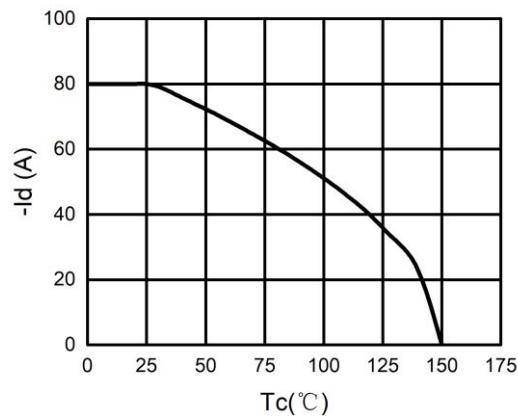
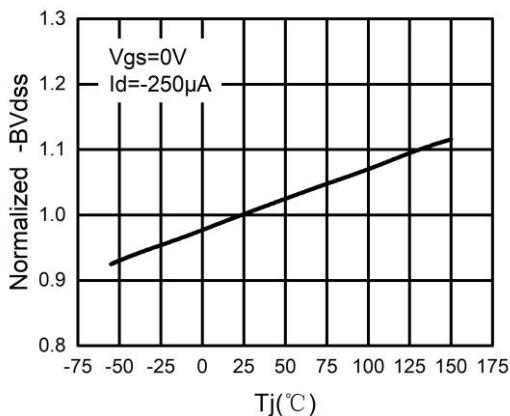
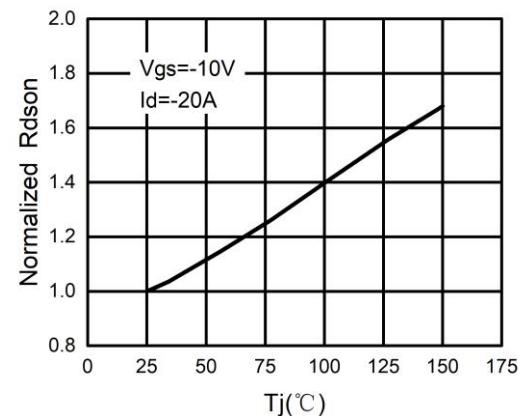
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V} I_{\text{D}}=-250\mu\text{A}$	-40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-40\text{V} V_{\text{GS}}=0\text{V}$	--	--	-1	nA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V} V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}} I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.7	-2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V} I_{\text{D}}=-20\text{A}$	--	4.3	5.3	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V} I_{\text{D}}=-20\text{A}$	--	5.5	6.9	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-5\text{V} I_{\text{D}}=-20\text{A}$	--	63	--	S
Gate Resistance	R_g	$F=1.0\text{MHz}$	--	2.2	--	Ω
Dynamic Characteristics <small>(Note 4)</small>						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-20\text{V} V_{\text{GS}}=0\text{V}$ $F=1.0\text{MHz}$	--	6638	--	PF
Output Capacitance	C_{oss}		--	545	--	PF
Reverse Transfer Capacitance	C_{rss}		--	345	--	PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-20\text{V} I_{\text{D}}=-20\text{A}$ $V_{\text{GS}}=-10\text{V} R_{\text{G}}=3\Omega$	--	16	--	nS
Turn-on Rise Time	t_r		--	17	--	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		--	68	--	nS
Turn-Off Fall Time	t_f		--	31	--	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=-20\text{V} I_{\text{D}}=-20\text{A}$ $V_{\text{GS}}=-10\text{V}$	--	118	--	nC
Gate-Source Charge	Q_{gs}		--	13	--	nC
Gate-Drain Charge	Q_{gd}		--	22	--	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V_{SD}	$V_{\text{GS}}=0\text{V} I_{\text{S}}=-20\text{A}$	--	--	-1.2	V
Diode Forward Current <small>(Note 2)</small>	I_{S}		--	--	-80	A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E_{AS} condition: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=15\text{V}$, $V_{\text{G}}=-10\text{V}$, $R_g=25\Omega$, $L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

• Typical Characteristics


Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Power Dissipation

Figure 4. Drain Current

Figure 5. BV_{DSS} vs Junction Temperature

Figure 6. $R_{DS(ON)}$ vs Junction Temperature

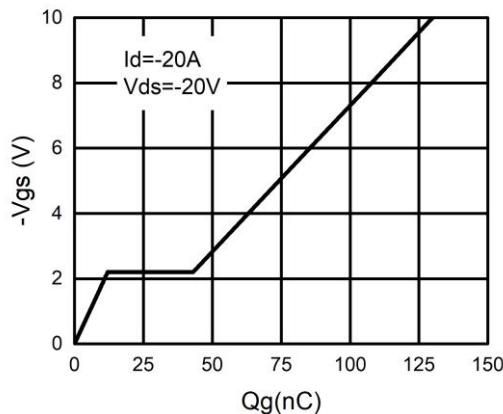


Figure 7. Gate Charge Waveforms

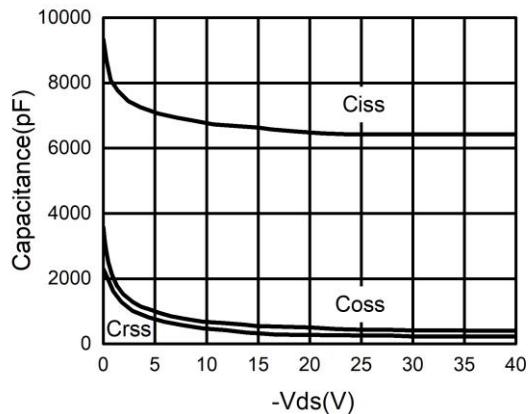


Figure 8. Capacitance

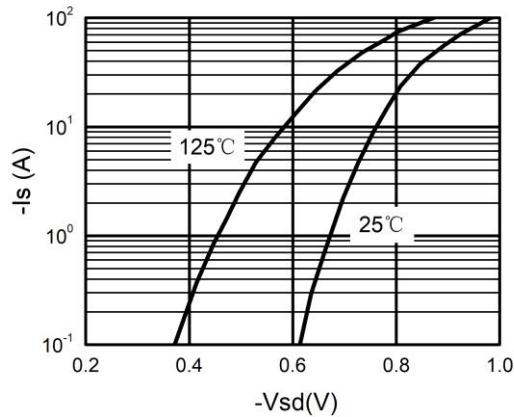


Figure 9. Body-Diode Characteristics

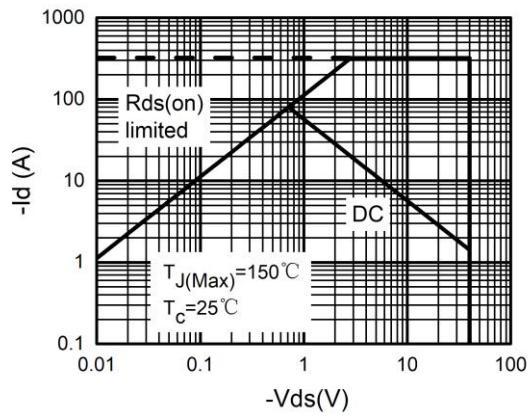
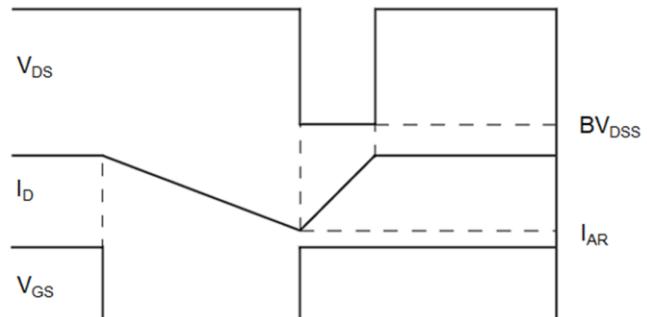
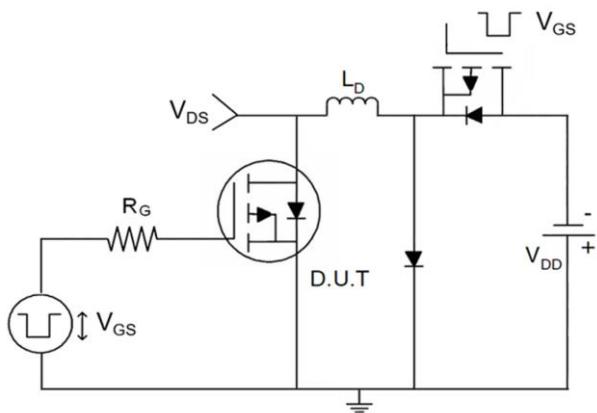
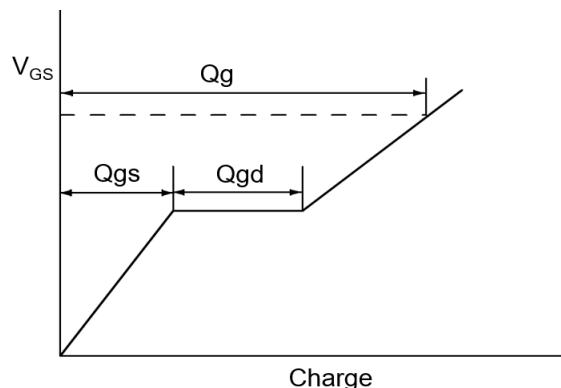
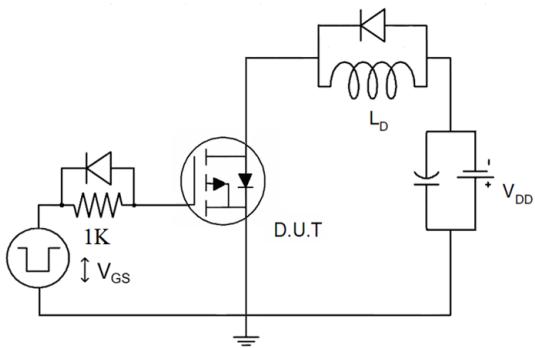


Figure 10. Maximum Safe Operating Area

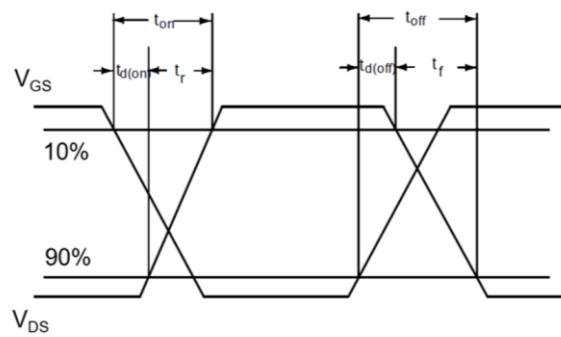
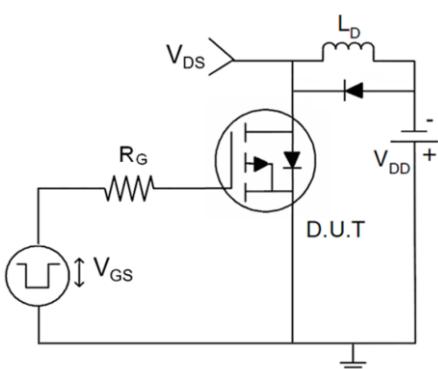
1) E_{AS} Test Circuits

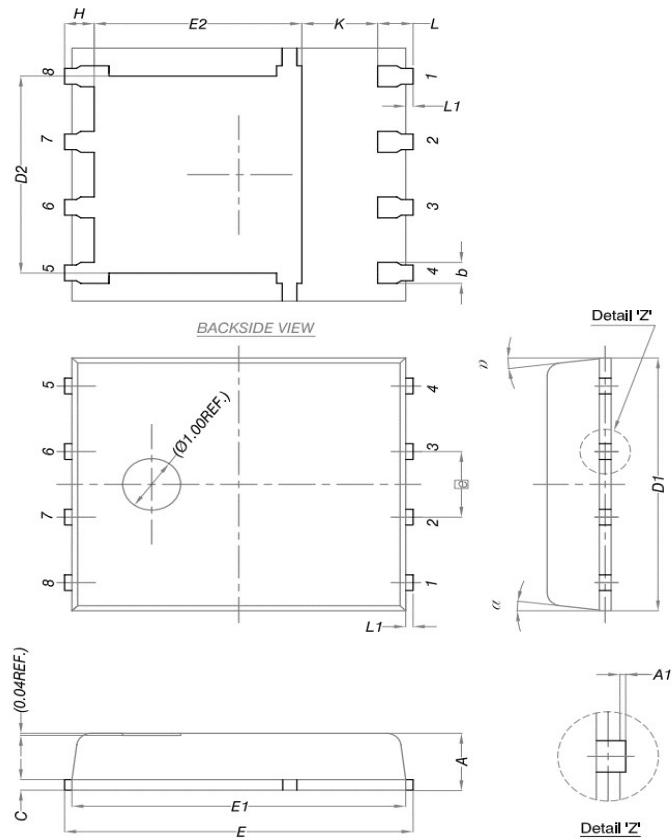


2) Gate Charge Test Circuit



3) Switch Time Test Circuit



•DFN5*6 Package Outline


DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
alpha	0°	-	12°